

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
Contact Info: ti.com/support
Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
Created on: 06/13/2022

Details for "UCC28085DR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
UCC28085DR	NIPDAU	Level-1-260C-UNLIM	TI AGUASCALENTES	D 8	3.91x4.9x1.58	84.7

*Total Device Mass
The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

				Homogeneous Material Level		Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.055485	99.998198	999982	0.065539	655
Precious Metals	Silver	7440-22-4	0.000001	0.001802	18	0.000001	0
Sub-Total			0.055486	100	1000000	0.06554	655
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.667728	79.00003	790000	0.788724	7887
Thermoplastics	Epoxy	85954-11-6	0.177497	20.99997	210000	0.20966	2097
Sub-Total			0.845225	100	1000000	0.998384	9984
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	24.025981	97.425003	974250	28.379606	283796
Copper and Its Alloys	Iron	7439-89-6	0.591864	2.4	24000	0.699113	6991
Copper and Its Alloys	Phosphorus	7723-14-0	0.003699	0.014999	150	0.004369	44
Copper and Its Alloys	Tin	7440-31-5	0.007398	0.029999	300	0.008739	87
Copper and Its Alloys	Zinc	7440-66-6	0.024661	0.1	1000	0.02913	291
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.007398	0.029999	300	0.008739	87
Sub-Total			24.661001	100	1000000	29.129695	291297
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.037097	95.120513	951205	0.043819	438
Precious Metals	Gold	7440-57-5	0.000304	0.779487	7795	0.000359	4
Precious Metals	Palladium	7440-05-3	0.001599	4.1	41000	0.001889	19
Sub-Total			0.039	100	1000000	0.046067	461
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	49.266743	88	880000	58.194118	581941
Other Plastics and Rubber	Carbon Black	1333-86-4	0.167955	0.3	3000	0.198389	1984
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.307917	0.55	5500	0.363713	3637
Thermoplastics	Epoxy	85954-11-6	6.24232	11.15	111500	7.373459	73735
Sub-Total			55.984935	100	1000000	66.12968	661297
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	3.07367	100	1000000	3.630634	36306
Sub-Total			3.07367	100	1000000	3.630634	36306
Total			84.659317			100	1000000

Important Note
The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information
There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

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For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.